

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are struck through. Please cancel Claims 6, 7, and 9-14.

1 (currently amended): A dicing/die-bonding film comprising:

a supporting base material,

a pressure-sensitive adhesive layer formed on at the supporting base material, and
a die-bonding adhesive layer formed on the pressure-sensitive adhesive layer, said
die-bonding adhesive layer being comprised of a work-attaching portion on which a work
is to be attached and a no-work-attaching portion other than the work-attaching portion,

wherein an interface between the pressure-sensitive adhesive layer and the die-
bonding adhesive layer comprises an interface (A) formed between corresponding to at the
work-attaching region portion in of the die-bonding adhesive layer and a portion (a) of the
pressure-sensitive adhesive layer in contact with the work-attaching portion, and

an interface (B) formed between corresponding to a part or a whole of the no-
work-attaching portion of the die-bonding adhesive layer and a portion (b) of the
pressure-sensitive adhesive layer in contact with the part or the whole of the no-work-
attaching portion a region other than the work-attaching region, and

wherein releasability between the pressure-sensitive adhesive layer and the die-
bonding adhesive layer at the interface (A) is higher than the releasability at the interface
(B).

2 (currently amended): The dicing/die-bonding film according to claim 1, wherein
adhesion of the pressure-sensitive adhesive layer to the die-bonding adhesive layer is different
between a region the portion (a) corresponding to the work-attaching region in the die-bonding
adhesive layer and a region the portion (b) corresponding to a part or the whole of the other region,
and satisfies the relationship:

the adhesion of the region portion (a) is lower than the adhesion of region portion (b).

3 (currently amended): The dicing/die-bonding film according to claim 1, wherein
adhesion of the work-attaching region portion in of the die-bonding adhesive layer to at the work
and to the region portion (a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the region (a).

4 (currently amended): The dicing/die-bonding film according to claim 1, wherein ~~the~~
part of the ~~region other than the no-work-attaching region portion~~ ~~in~~ of the die-bonding adhesive
layer is a dicing ring-attaching ~~region~~ ~~portion to which a dicing ring is to be attached~~.

5 (currently amended): The dicing/die-bonding film according to claim 4, wherein
adhesion of the dicing ring-attaching ~~region~~ ~~portion~~ ~~in~~ of the die-bonding adhesive layer to ~~at~~ the
dicing ring and to a ~~region~~ ~~portion~~ (b') ~~of the pressure-sensitive adhesive layer in contact with~~
~~corresponding to the dicing ring-attaching region portion~~ satisfies the relationship:

the adhesion to the dicing ring is lower than the adhesion to the ~~region~~ ~~portion~~ (b').

6-7 (canceled)

8 (currently amended): The dicing/die-bonding film according to claim 1, wherein the
pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and
the ~~region~~ ~~portion~~ (a) corresponding to the work-attaching ~~region~~ ~~portion~~ is irradiated with
radiations.

9-14 (canceled)